



# DOH - AB L1&L2 Flex Cable v1.1.3 - 2-layer Flex-Rigid Board

## Material Selection

Polyimide  
Permittivity @ 100MHz:  
Permittivity @ 1GHz:  
Loss Tangent @ 100MHz:  
Loss Tangent @ 1GHz:  
Lead Free Assembly Compatible

Solder resist colour: green  
Silkscreen print colour: white

## Surface Finish

On top and bottom layer surfaces:  
electroless nickel immersion gold

## Holes / Drilling

Drill files contain finished hole diameters  
Drilling layer pairs: 1-2

## Board Outline

Contour routed with break-away tabs

## Element Counts

(for reference only)

Nets: 9  
Pads: 60  
Tracks: 220  
Polygons: 0  
Holes: 14  
Vias: 14

## Non-standard Tolerances

Holes sized 0.2mm may be plugged by plating. These are all vias.  
For them we do not care the finished hole sizes.

## Board Layer Stack / Drill Layer-Pairs



## Layer Name Gerber

Top Overlay	.gto
Top Solder Mask	.gts
GND	.g1
Signal Layer	.gbl
Bottom Solder Mask	.gbs
Bottom Overlay	.gbo
Board Outline	.gml

\*35um final after plating

Total Laminated Thickness on Rigid Region: 0.3mm +/- 0.05mm !

## Controlled Impedance Reference

Diff. trace width/space on bottom layer (microstrip) 75 ohms +/- 10% : 0.1/0.1mm